

anisotropic conductive adhesive; the bonding device comprising:

a base film;

a conductive layer having a first side and a second side wherein a first side of the conductive layer is attached the base film;

an overcoat layer attached to a first portion of a second side of the conductive layer; and

a conductive element attached to a second portion of the second side of the conductive layer wherein the conductive element is adapted to form an electrical conduit between the conductive layer and the attached bonding pad.

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28. (New) A bonding device according to claim 27 wherein the overcoat layer comprises at least two sections arranged on the second side of the conductive layer such that a portion of each of the two sections overlap a portion of the bonding pad when the bonding device is attached to the bonding pad.

29. (New) A bonding device according to claim 27 wherein the anisotropic conductive adhesive surrounds the conductive element when the bonding device is attached to the bonding pad.

30. (New) A bonding device according to claim 27 wherein conductive element comprises gold.

31. (New) A bonding device according to claim 27 wherein the anisotropic conductive adhesive comprises anisotropic conductive film.

32. (New) A bonding device according to claim 27 wherein the conductive element comprises a bump having a height of about 12 to 38 μm .

33. (New) A bonding device according to claim 27 wherein the conductive element comprises a gold ball.

34. (New) A bonding device according to claim 27 wherein the conductive element comprises a filling that completely occupies a space formed by the bonding pad, the conductive layer, and the overcoat layer when the bonding device is attached to the bonding pad.

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35. (New) A bonding device according to claim 34 wherein the filling is less than 10 μm thick.

36. (New) A bonding device according to claim 34 wherein the filling is about 10 to 38 μm thick.

37. (New) A bonding device according to claim 34 wherein the filling is thicker than or equal to the overcoat layer.

38. (New) A bonding device according to claim 34 wherein the filling is thinner than the overcoat layer.